

**TM10N06D**

**N-Channel Enhancement Mosfet**

**General Description**

- Low  $R_{DS(ON)}$
- RoHS and Halogen-Free Compliant

**Applications**

- Load switch
- PWM

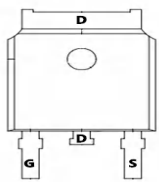
**General Features**

$V_{DS} = 60V$   $I_D = 10 A$   
 $R_{DS(ON)} = 65 m\Omega$  (typ.) @  $V_{GS} = 10V$

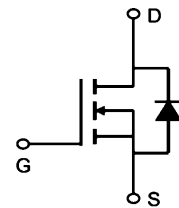
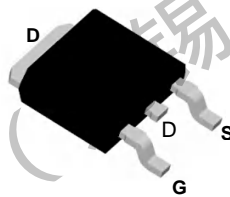
100% UIS Tested  
 100%  $R_g$  Tested



D:TO-252-3L



Marking: 10N06



**Absolute Maximum Ratings** ( $T_C = 25^\circ C$  Unless Otherwise Noted)

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	60	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D @ T_C = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	10	A
$I_D @ T_C = 100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	6.2	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	22	A
$P_D @ T_A = 25^\circ C$	Total Power Dissipation <sup>3</sup>	1.2	W
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ C$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ C$

**Thermal Data**

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-ambient <sup>1</sup>	---	62	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	---	6.6	$^\circ C/W$

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**Electrical Characteristics** ( $T_J=25^{\circ}\text{C}$  unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
<b>Static Parameter</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	60	-	-	V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=60V, V_{GS}=0V$	-	-	1	$\mu A$
		$V_{DS}=60V, V_{GS}=0V, T_J=150^{\circ}\text{C}$	-	-	100	
Gate-Body Leakage Current	$I_{GSS}$	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	$\pm 100$	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1	2	3	V
Static Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=3A$	-	65	74	m $\Omega$
		$V_{GS}=4.5V, I_D=3A$	-	75	92	
Diode Forward Voltage	$V_{SD}$	$I_S=3A, V_{GS}=0V$	-	0.85	1.2	V
Gate resistance	$R_G$	$f=1\text{MHz}, \text{Open drain}$	-	2	-	$\Omega$
Maximum Body-Diode Continuous Current	$I_S$		-	-	10	A
<b>Dynamic Parameters</b>						
Input Capacitance	$C_{iss}$	$V_{DS}=30V, V_{GS}=0V, f=1\text{MHz}$	-	400	-	pF
Output Capacitance	$C_{oss}$		-	28	-	
Reverse Transfer Capacitance	$C_{rss}$		-	22	-	
<b>Switching Parameters</b>						
Total Gate Charge	$Q_g$	$V_{GS}=10V, V_{DS}=30V, I_D=3A$	-	10	-	nC
Gate-Source Charge	$Q_{gs}$		-	1.7	-	
Gate-Drain Charge	$Q_{gd}$		-	2.1	-	
Reverse Recovery Charge	$Q_{rr}$	$I_F=3A, di/dt=100A/\mu s$	-	7	-	nC
Reverse Recovery Time	$t_{rr}$		-	33	-	ns
Turn-on Delay Time	$t_{D(on)}$	$V_{GS}=10V, V_{DD}=30V, R_L=20\Omega, R_{GEN}=3\Omega$	-	3.6	-	ns
Turn-on Rise Time	$t_r$		-	17.6	-	
Turn-off Delay Time	$t_{D(off)}$		-	13	-	
Turn-off fall Time	$t_f$		-	23	-	

A. Repetitive rating; pulse width limited by max. junction temperature.

B.  $P_d$  is based on max. junction temperature, using junction-case thermal resistance.

C. The value of  $R_{\theta JA}$  is measured with the device mounted on the minimum recommend pad size, in the still air environment with  $T_A=25^{\circ}\text{C}$ . The maximum allowed junction temperature of  $150^{\circ}\text{C}$ . The value in any given application depends on the user's specific board design.

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Typical Electrical and Thermal Characteristics Diagrams

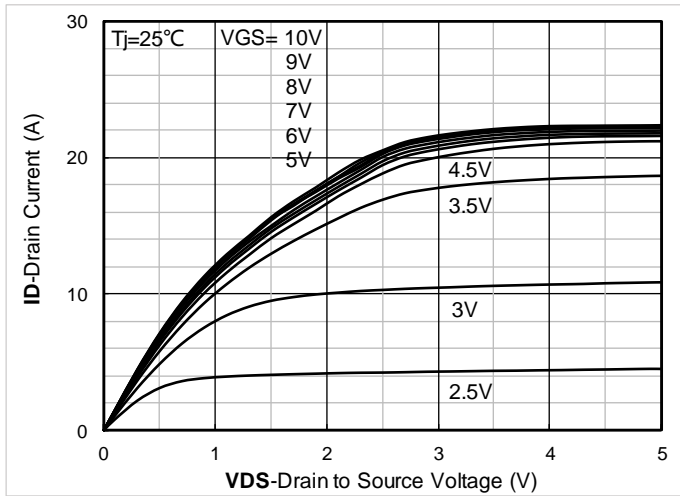


Figure 1. Output Characteristics

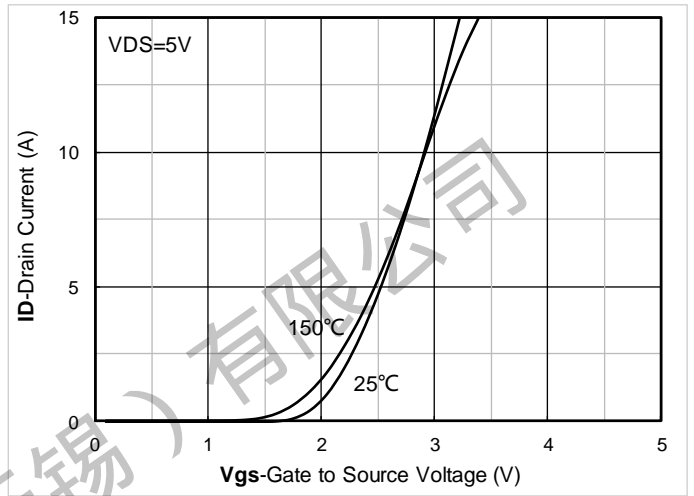


Figure 2. Transfer Characteristics

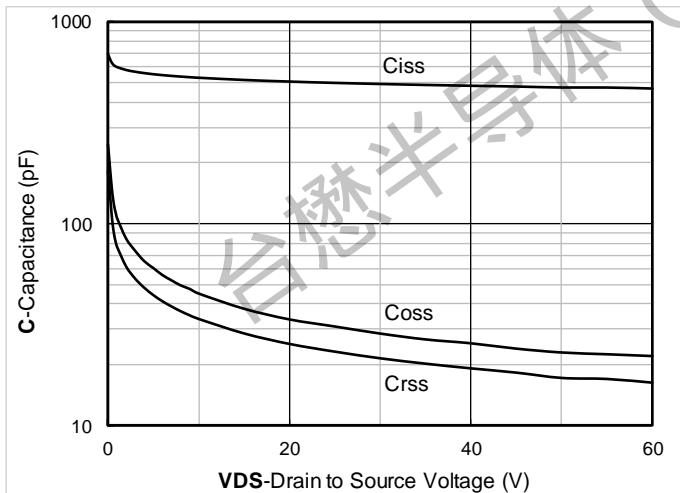


Figure 3. Capacitance Characteristics

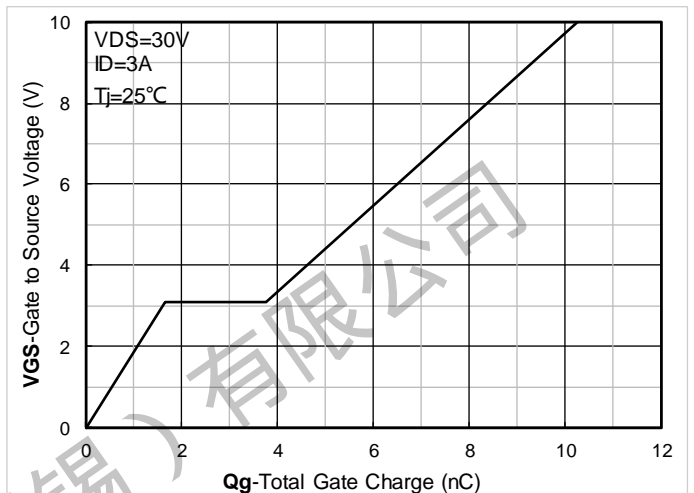


Figure 4. Gate Charge

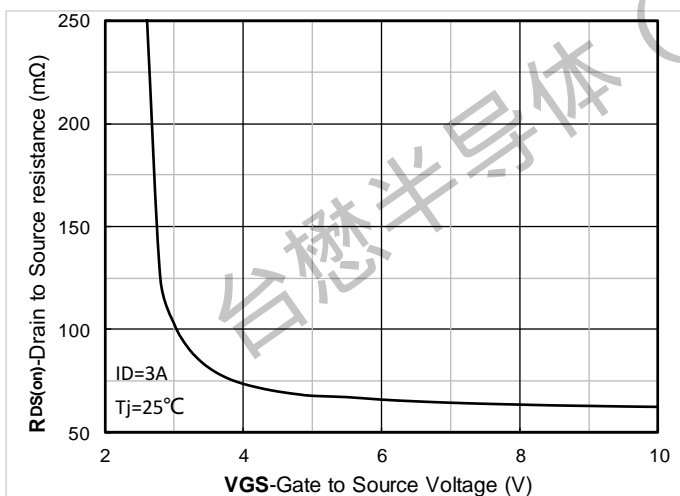


Figure 5. On-Resistance vs Gate to Source Voltage

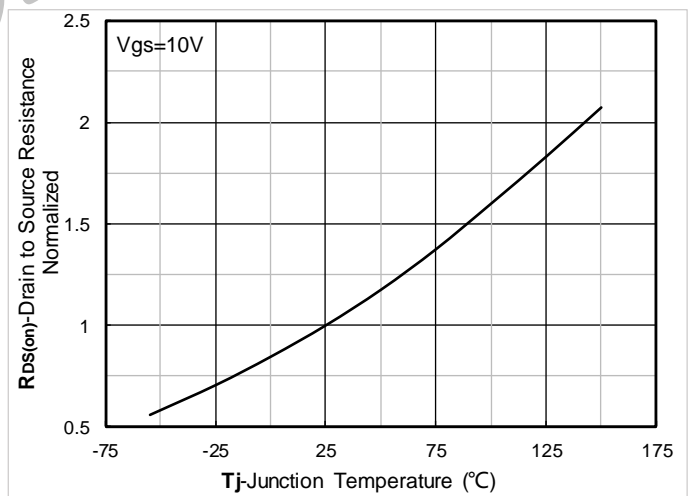


Figure 6. Normalized On-Resistance

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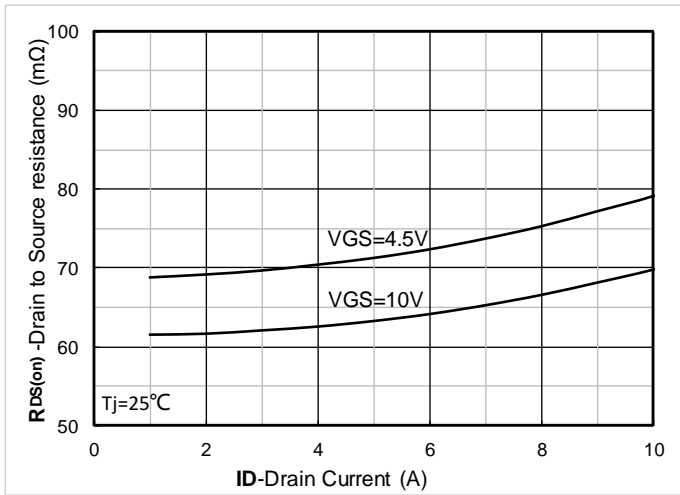


Figure 7. RDS(on) VS Drain Current

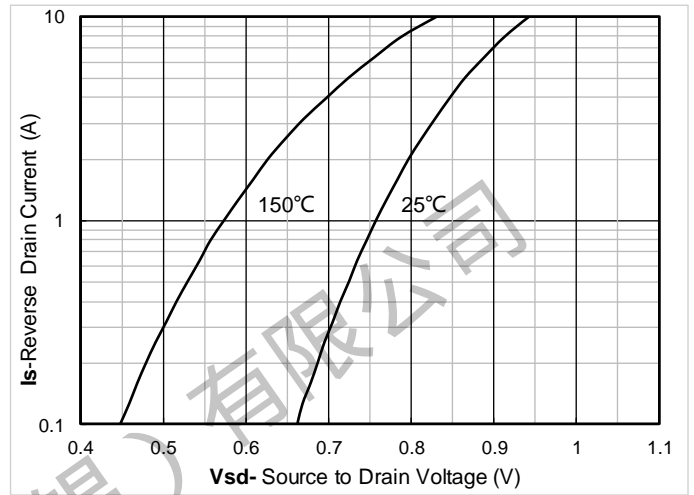


Figure 8. Forward characteristics of reverse diode

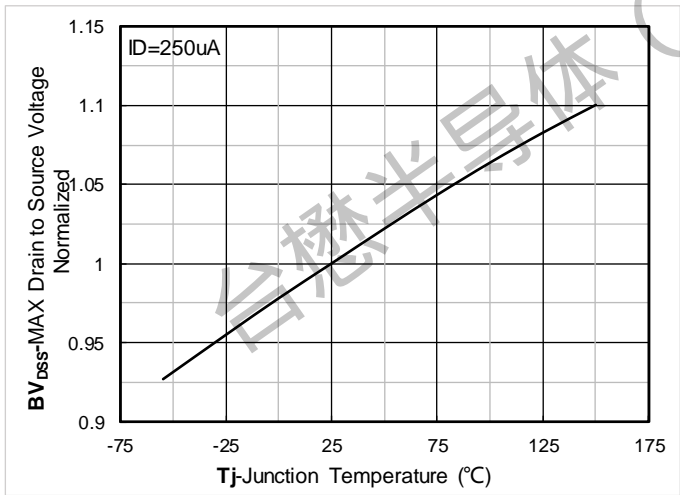


Figure 9. Normalized breakdown voltage

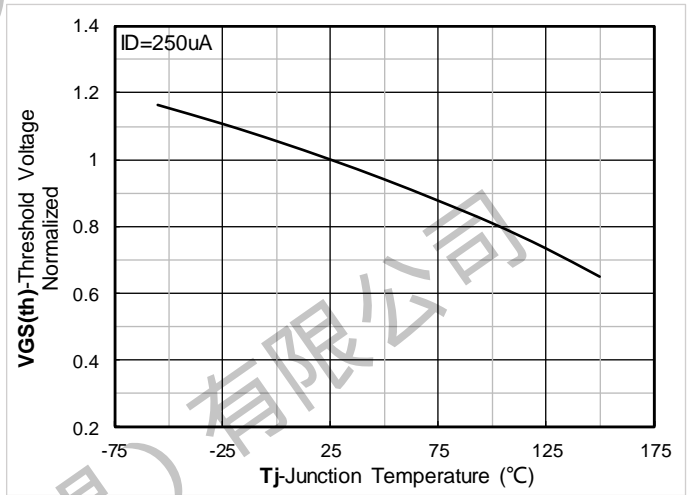


Figure 10. Normalized Threshold voltage

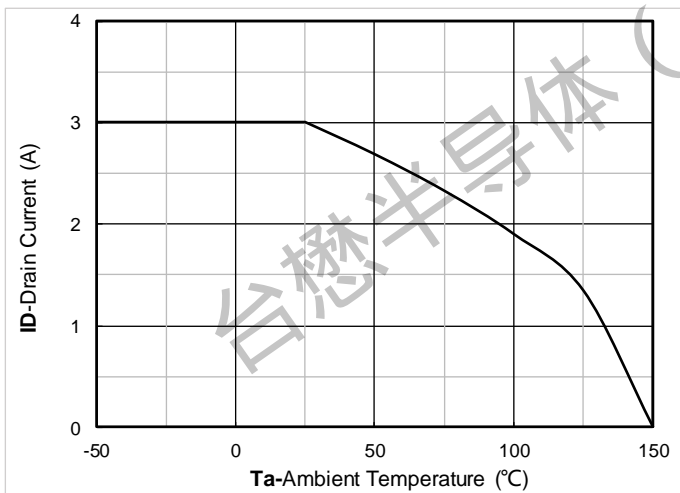


Figure 11. Current dissipation

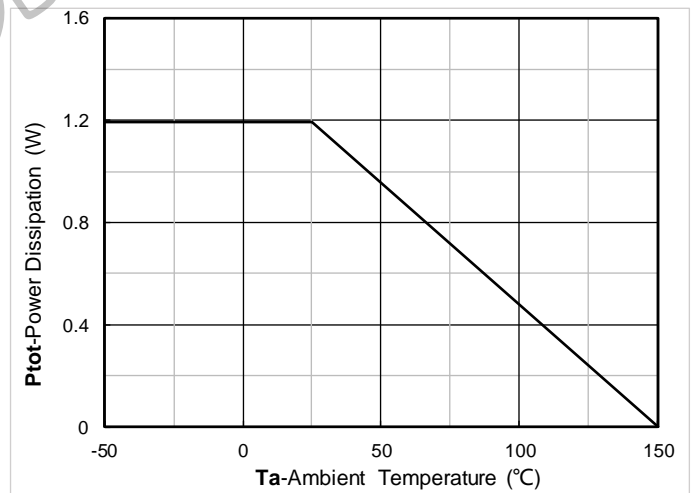


Figure 12. Power dissipation

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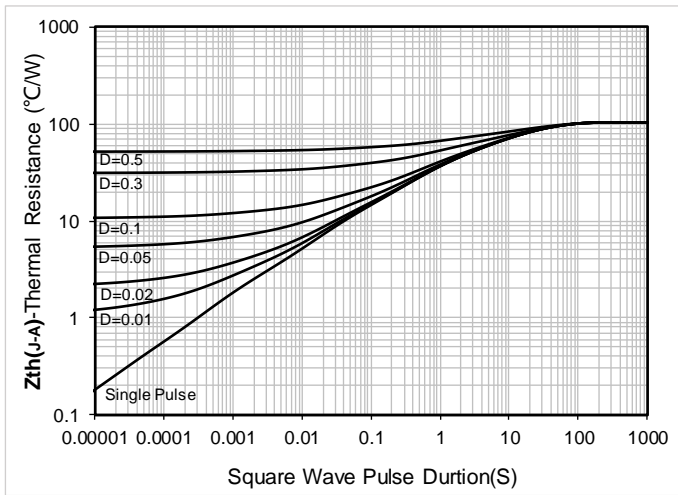


Figure 13. Maximum Transient Thermal Impedance

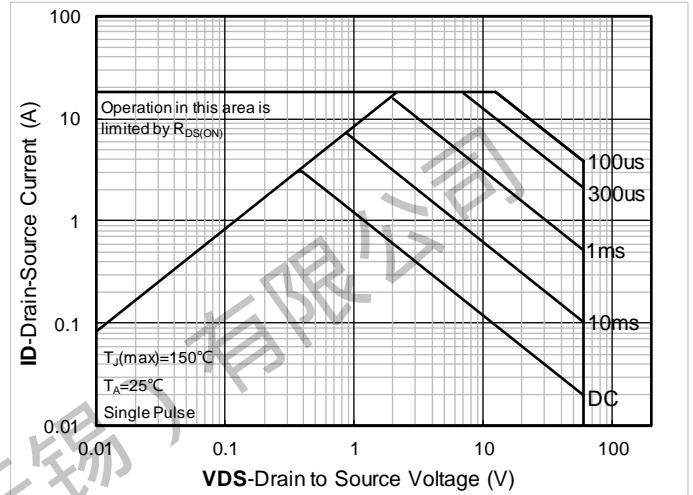
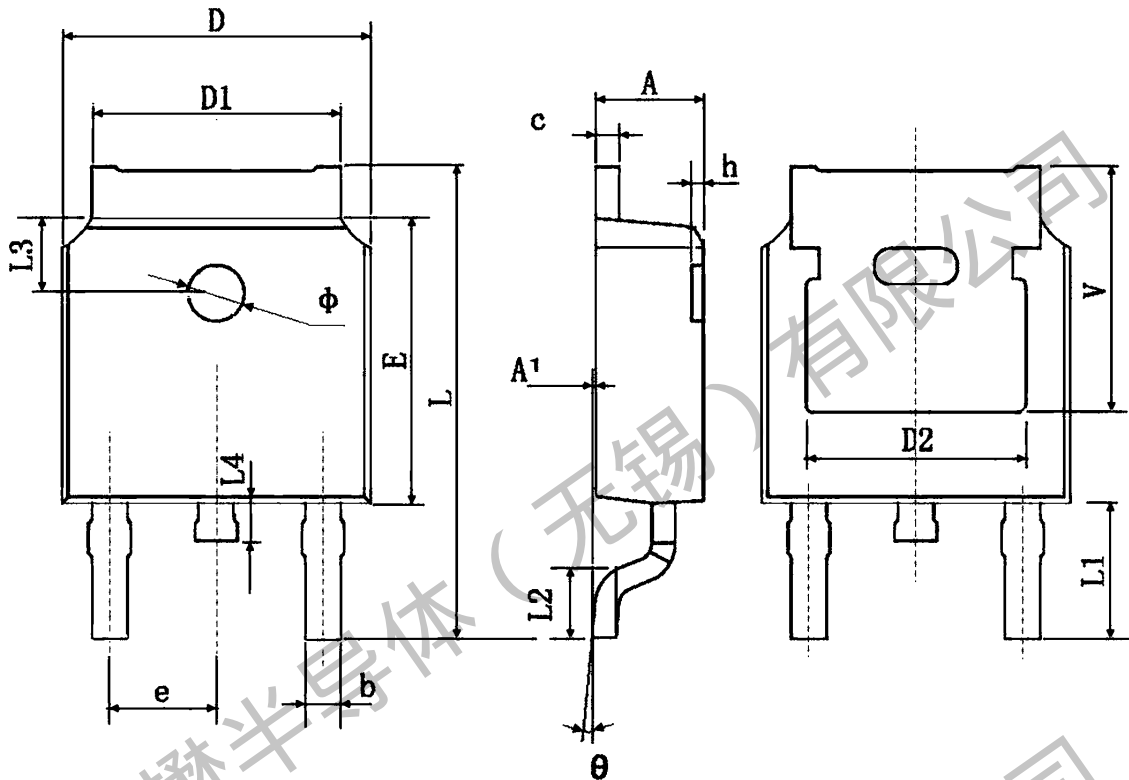


Figure 14. Safe Operation Area

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Package Mechanical Data: TO-252-3L

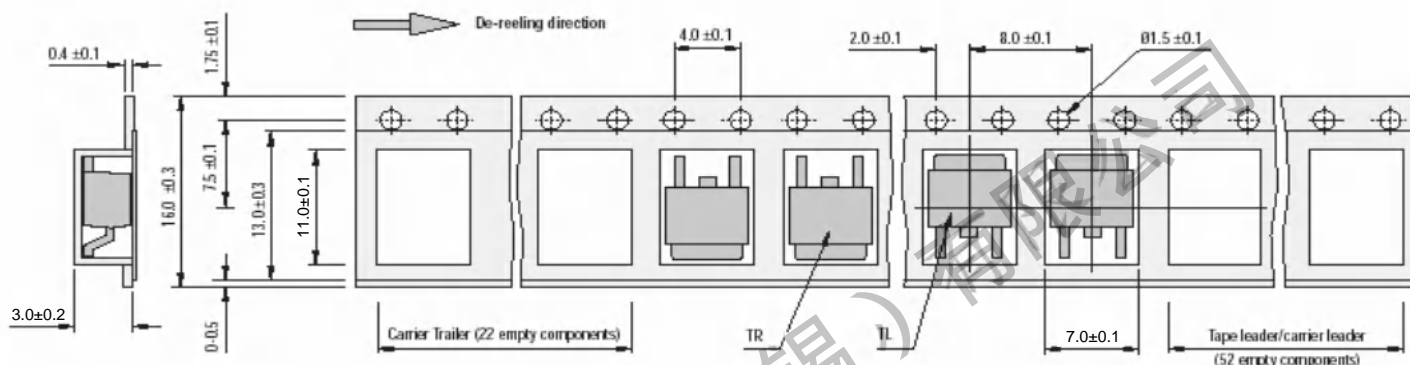


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830 TYP.		0.190 TYP.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 TYP.		0.114 TYP.	
L2	1.400	1.700	0.055	0.067
L3	1.600 TYP.		0.063 TYP.	
L4	0.600	1.000	0.024	0.039
phi	1.100	1.300	0.043	0.051
theta	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
v	5.350 TYP.		0.211 TYP.	

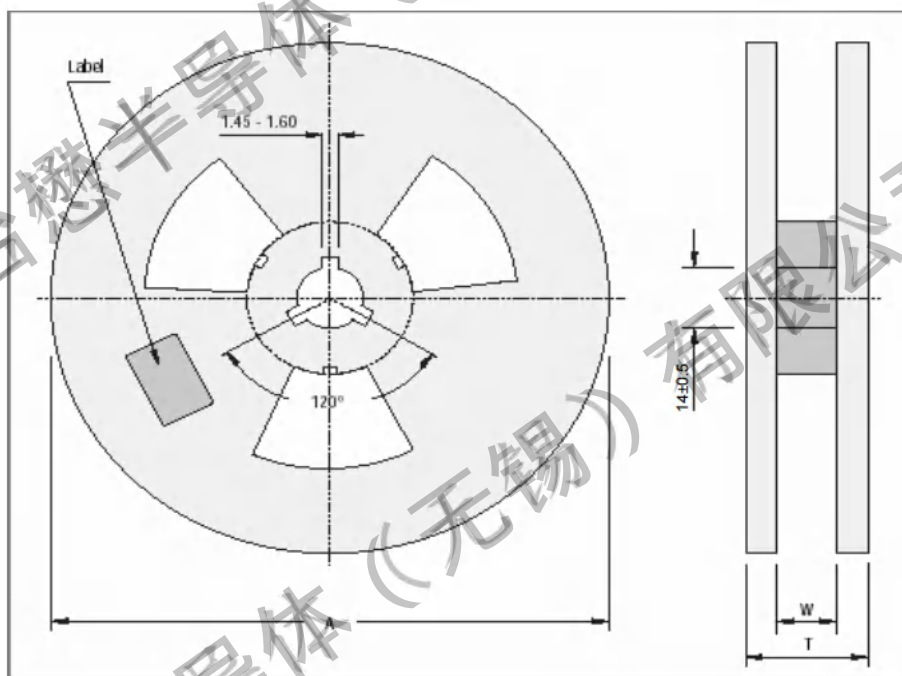
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TO-252-3L Embossed Carrier Tape



TO-252-3L Reel



All Dimensions are in mm.

Reel Specifications				
Package	Tape Width	Reel Dia. A - Max	Inside Thickness W	Reel Thickness T - max
TO-252-3L	16	330	18.0 ±1.5	20

**Packaging Information**

REEL	Reel Size	Box	Box Size(mm)	Carton	Carton Size(mm)	G.W.(kg)
2,500 pcs	13 inch	5,000 pcs	355×370×50	25,000 pcs	380×275×380	



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#### Revision history:

Date	Rev	Description	Page
2023.05.09	23.05	Original	